IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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For: CHIP-SCALE ELECTRONIC COMPONENT PACKAGE

Examiner: Minh Nguyen

Art Unit: 3992

Applicants: Lakin et al.

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STATEMENT UNDER 37 CFR § 3.73(b)

TriQuint Semiconductor, Inc., a corporation, states that it is the assignee of the entire right, title, and interest in the patent application/patent identified above by virtue of a chain of title from the inventors, to the current assignee of the patent application/patent identified above, as follows:

Reel 009325, Frame 0921, recorded on July 14, 1998.

- From: Kenneth Meade Lakin, Ralph Edward Rose, and Kevin Thomas McCarron
 To: TFR Technologies, Inc.

 The document was recorded in the United States Patent and Trademark Office at
- 2. From: TFR Technologies, Inc.

To: TriQuint Semiconductor, Inc.

The document was recorded in the United States Patent and Trademark Office at Reel 016844. Frame 0147, recorded on July 20, 2005.

The undersigned is authorized to sign this Power of Attorney by Assignee on behalf of the assignee.

Executed at <u>Hillsboro, OR</u> on the <u>4th</u> day of <u>June</u> , 2010.

TriQuint Semiconductor, Inc.

By Steve Buhaly

Title: Vice President and CFO